



# SOT96-1

plastic, small outline package; 8 leads; 1.27 mm pitch; 4.9 mm x 3.9 mm x 1.75 mm body

7 December 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	SO8
<b>Package type industry code</b>	SO8
<b>Package style descriptive code</b>	SO (small outline)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	076E03
<b>JEDEC package outline code</b>	MS-012
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	18-02-2003
<b>Manufacturer package code</b>	98ASA01364D

Table 1. Package summary

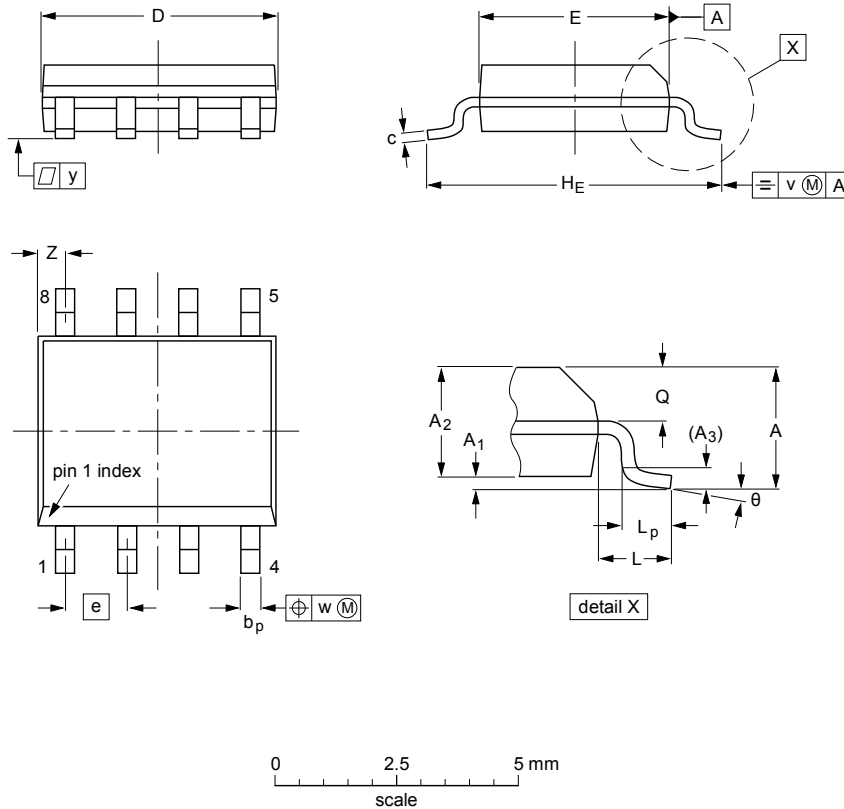
Parameter	Min	Nom	Max	Unit
package length	4.8	4.9	5	mm
package width	3.8	3.9	4	mm
seated height	-	1.75	-	mm
package height	1.25	1.35	1.45	mm
nominal pitch	-	1.27	-	mm
actual quantity of termination	-	8	-	



2 Package outline

SO8: plastic small outline package; 8 leads; body width 3.9 mm

SOT96-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.20 0.19	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

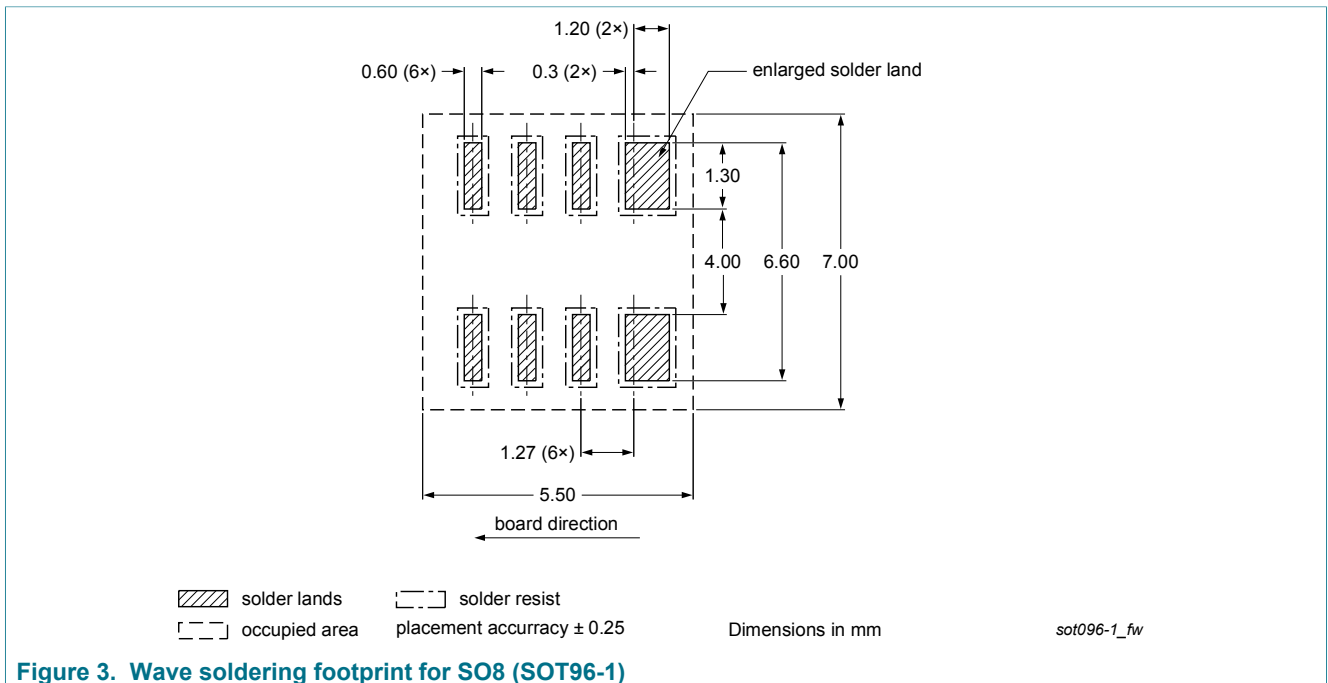
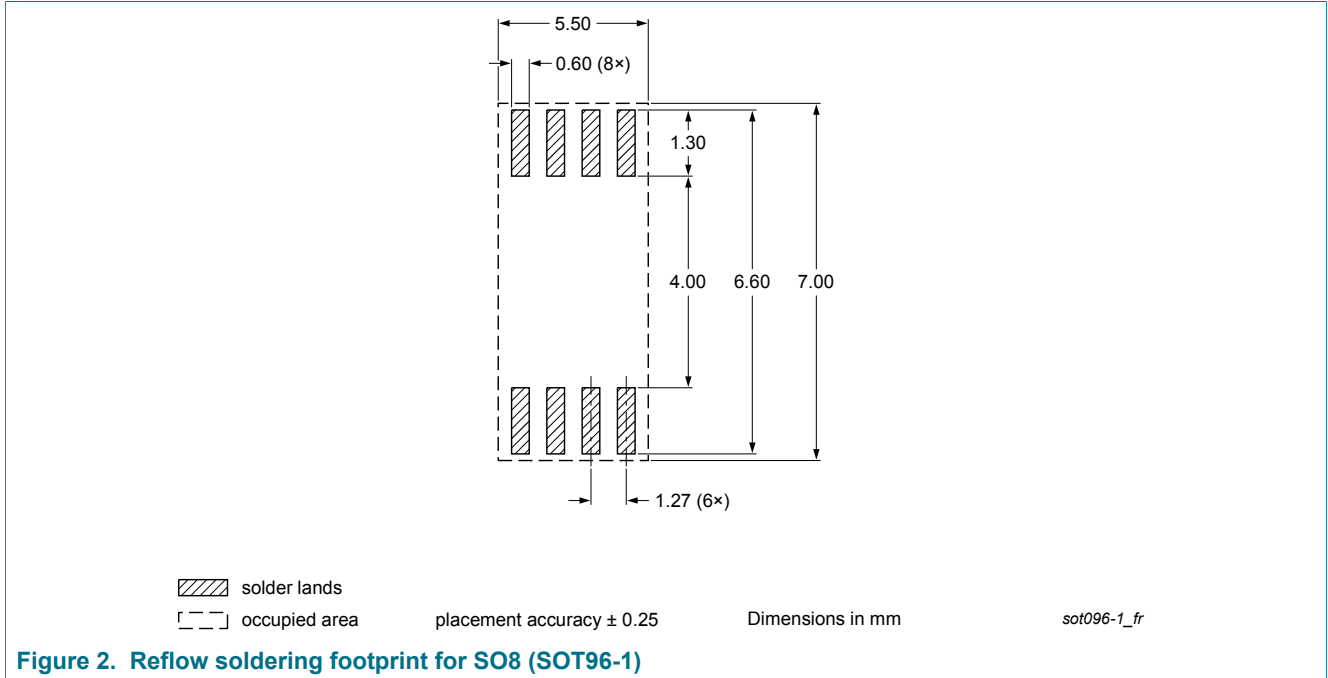
Notes

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT96-1	076E03	MS-012			99-12-27 03-02-18

Figure 1. Package outline SO8 (SOT96-1)

### 3 Soldering



## 4 Legal information

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